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- (81) 指定国(除另有指明, 要求每一种可提供的国家保护): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW。

(54) **Title:** SUBSTRATE BEARING DEVICE AND SUBSTRATE PROCESSING APPARATUS

(54) 发明名称: 基片承载装置及基片处理设备

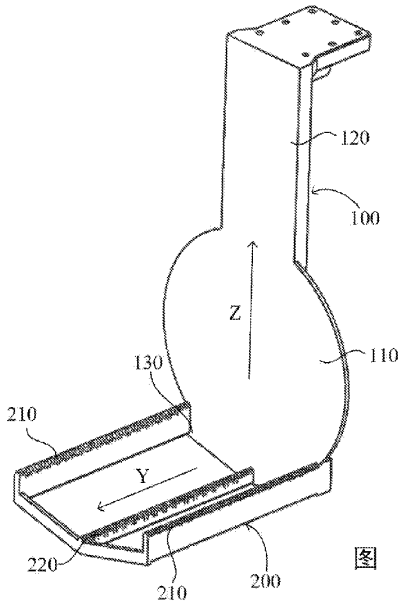


图 1

(57) **Abstract:** The present invention relates to the field of semiconductor apparatuses. Disclosed are a substrate bearing device and a substrate processing apparatus. The substrate bearing device comprises: a connecting member comprising a connecting main body extending in the vertical direction; and a bearing member connected to the connecting member, extending in the horizontal direction, and bearing a plurality of substrates in such a manner that the plurality of substrates are parallel to the vertical direction, wherein the plurality of substrates comprise a first substrate adjacent to the main surface of the connecting member, the connecting member further comprises a rectifying part, the main surface of the rectifying part is flush with the main surface of the connecting main body, and the rectifying part is configured such that when the bearing member bears the substrates, the orthographic projection of the first substrate on the rectifying part is located in the rectifying part. According to the present invention, the flow field of the surface of the first substrate close to the rectifying part is greatly improved, thereby improving the cleaning effect of the first substrate, the rectifying part is flush with the main surface of the connecting member, so that during cleaning, the flow field is more stable.

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(84) 指定国(除另有指明, 要求每一种可提供的地区保护): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), 欧亚 (AM, AZ, BY, KG, KZ, RU, TJ, TM), 欧洲 (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG)。

本国际公布:
— 包括国际检索报告(条约第21条(3))。

(57) 摘要: 本发明公开了一种基片承载装置及基片处理设备, 涉及半导体设备领域。一种基片承载装置, 包括: 连接件, 包括沿竖直方向延伸的连接主体; 承载件, 连接于所述连接件, 所述承载件沿水平方向延伸, 以多个基片平行于所述竖直方向的方式承载所述多个基片, 其中, 多个基片中包括与所述连接件的主面相邻的第一基片; 其中, 连接件还包括整流部, 所述整流部的主面与所述连接主体的主面平齐, 整流部被配置为: 当所述承载件上承载基片时, 第一基片在所述整流部上的正投影位于所述整流部内。本发明使得第一基片靠近整流部的一面的流场得到了极大地改善, 从而提升了第一基片的清洗效果, 整流部与连接件的主面平齐, 在清洗过程中, 流场更为稳定。